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3.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER
Product Summary (@T_A = +25°C)

V _{RRM} (V)	I _O (A)	V _F (V)	I _R (μA)
1000	3.0	1.1	5

Description and Applications

Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

Features and Benefits

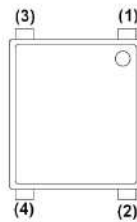
- Glass Passivated Die Construction
- Compact, Thin Profile Package Design
- Reliable Robust Construction
- Ideal for SMT Manufacturing
- Rated at 1000V PRV
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

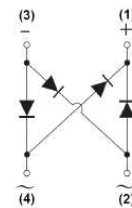
- Case: MSBL
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 **(e3)**
- Polarity: As marked on Body
- Weight: 0.216 grams (Approximate)



Top View



Pin Diagram

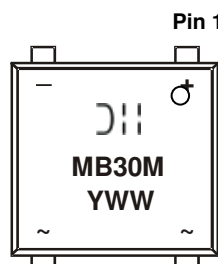


Internal Schematic

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
MSB30M-13	Commercial	MSBL	2,500/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


MB30M= Product Type Marking Code
 YWW = Manufacturers' Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 6 = 2016)
 WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	1000	V
RMS Reverse Voltage	V _{R(RMS)}	700	V
Average Rectified Output Current @ T _C = +120°C	I _O	3.0	A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	100	A
Non-Repetitive Peak Forward Surge Current, 1.0ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	200	A
I ² t Rating for Fusing (1ms < t < 8.3ms)	I ² t	41.5	A ² S

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element)	R _{θJA}	11	°C/W
Typical Thermal Resistance, Junction to Case	R _{θJC}	8	°C/W
Typical Thermal Resistance, Junction to Lead	R _{θJL}	15	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	1,000	—	—	V	I _R = 5μA
Forward Voltage (Per Element)	V _F	—	0.80	1.02	V	I _F = 1.5A, T _A = +25°C I _F = 1.5A, T _A = +125°C I _F = 3.0A, T _A = +25°C I _F = 3.0A, T _A = +125°C
Leakage Current (Note 6) (Per Element)	I _R	—	0.31	5	μA	V _R = 1,000V, T _A = +25°C V _R = 1,000V, T _A = +125°C
Total Capacitance (Note 7)	C _T	—	35	—	pF	V _R = 4V, f = 1.0MHz

Notes: 5. Device mounted on 15mm*12mm*1.6mm AL pad attach 195mm*110mm*10mm steel plate.
6. Short duration pulse test used to minimize self-heating effect.
7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

FIG.1-FORWARD CURRENT DERATING CURVE

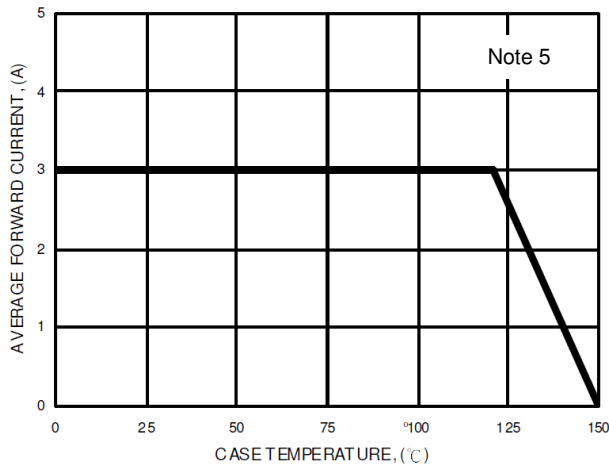


FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

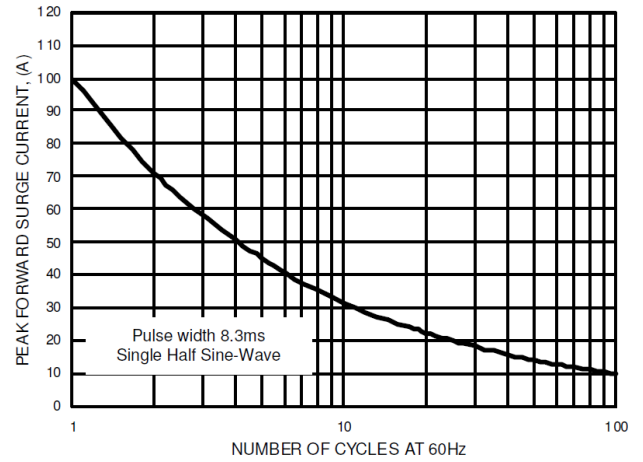


FIG.3- TYPICAL FORWARD CHARACTERISTICS

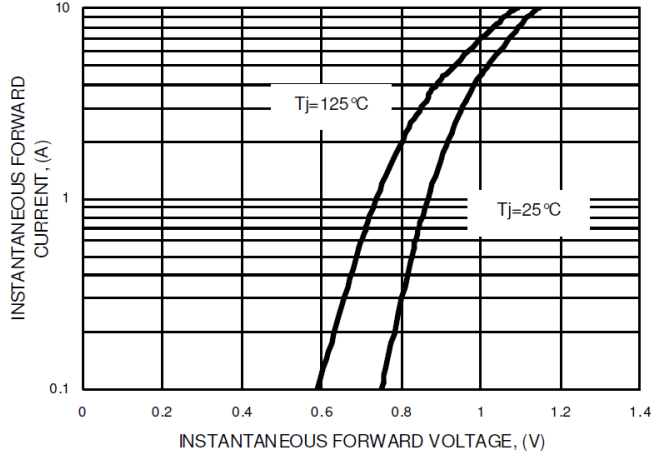


FIG.4- TYPICAL TOTAL CAPACITANCE

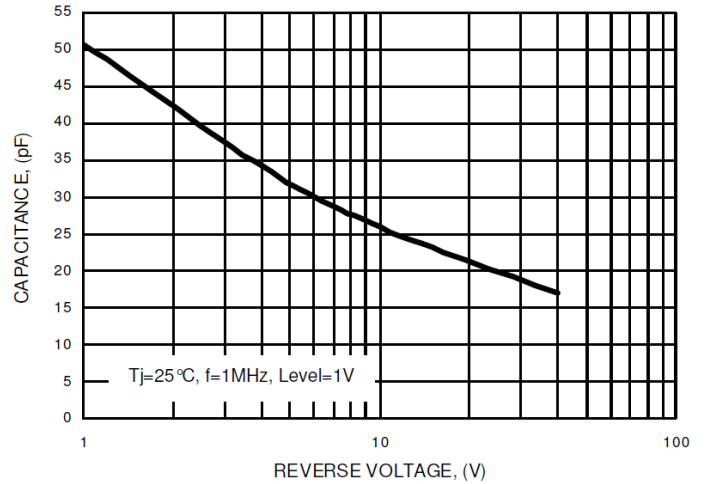


FIG.5- TYPICAL REVERSE CHARACTERISTICS

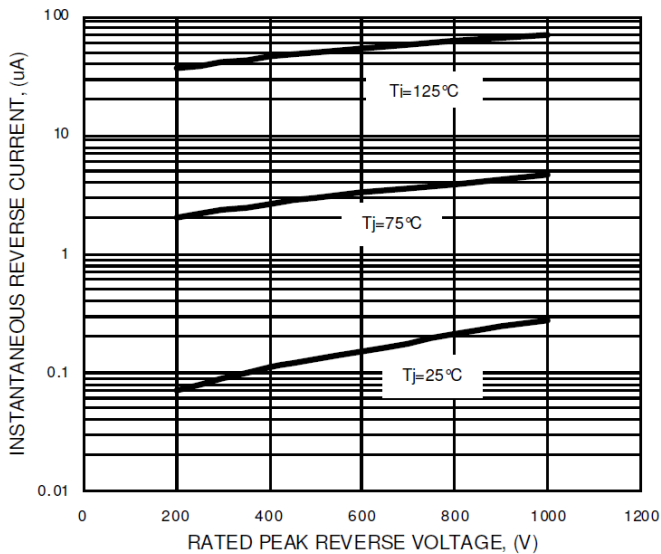
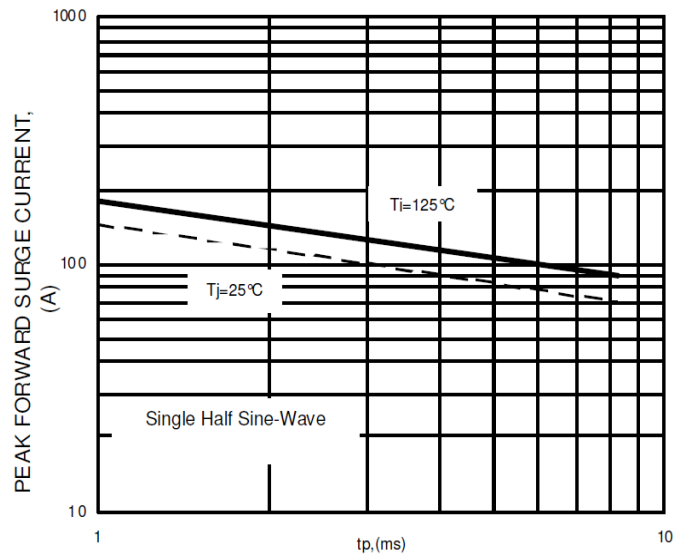


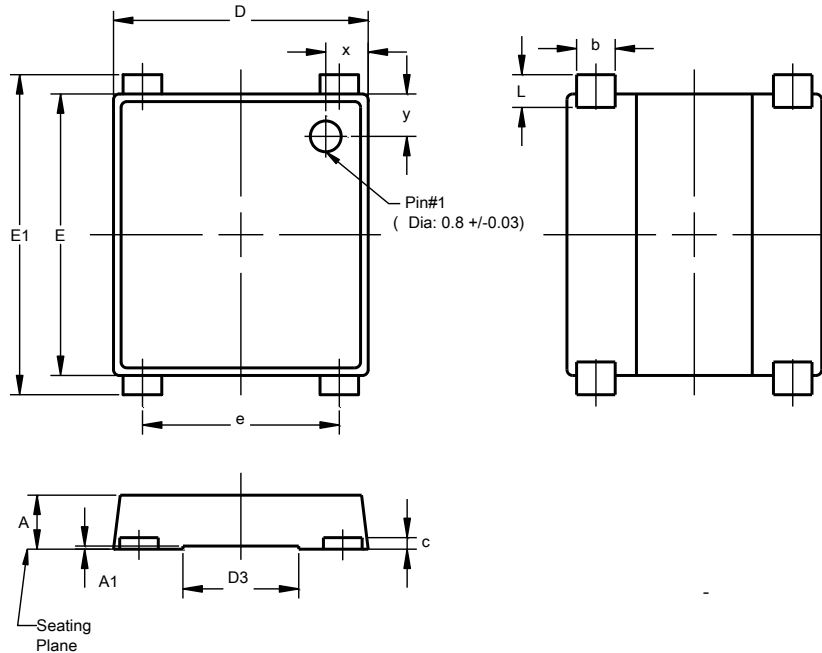
FIG.6- NON-REPETITIVE SURGE CURRENT



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

MSBL

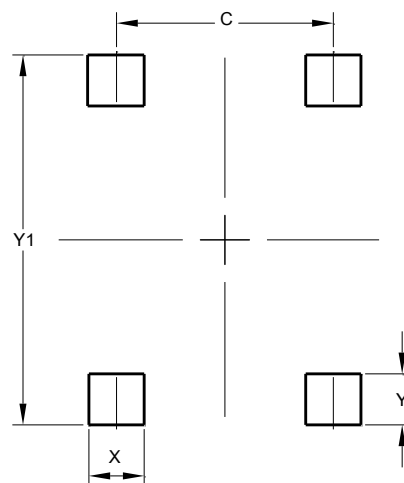


MSBL			
Dim	Min	Max	Typ
A	1.30	1.50	1.40
A1	0.04	0.08	0.06
b	0.95	1.15	1.00
c	0.27	0.40	0.30
D	6.50	6.70	6.60
D3	2.90	3.10	3.00
E	7.20	7.40	7.30
E1	7.90	8.60	8.30
e	5.00	5.20	5.10
L	0.65	1.05	0.85
x	0.95	1.25	1.10
y	0.95	1.25	1.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

MSBL



Dimensions	Value (in mm)
C	5.10
X	1.30
Y	1.20
Y1	8.70

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